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(54) WIRING BOARD

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## (57)**ABSTRACT**

A wiring board includes an insulating base having a first principal surface, and a second principal surface opposite to the first principal surface, a first through hole formed in the base, a first conductive layer provided inside the first through hole, a first insulating layer covering the first principal surface, a second insulating layer covering the second principal surface, a second through hole formed in the first insulating layer, the base, and the second insulating layer, a magnetic material provided inside the second through hole, a third through hole famed in the magnetic material, and a second conductive layer provided inside the third through hole.

